



To the Honorable Commissioner of Patent

102110582

attached original documents or copy thereof.

1 Name of conveying party(ies):

Tsu shih  
Sung Ming Jang

05/23/02

2 Name and address of receiving party(ies):

Taiwan Semiconductor Manufacturing Co. Ltd.  
No. 121 Park Avenue 3  
Science-Based Industrial Park  
Hsin-Chu, Taiwan, R.O.C.

Additional name(s) & address(es) attached  Yes  No

3 Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name

Other:

Execution Date: February 28, 2002

4 Application number(s) or patent number(s):

10/154463

If this document is being filed together with a new application, the execution date of the application is: 02-28-02

A. Patent Application No(s).

B. Patent No(s)

Additional numbers attached?  Yes  No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG  
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6 Total number of applications and patents involved:

1

7 Total fee (37 CFR 3.41)

\$40.00

- Enclosed
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8 Deposit Account Number: 50-0484

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02 FC:581

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9 Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung  
Name of Person Signing  
Registration No. 31,311

Signature

May 23, 2002  
Date

Total number of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to:  
Commissioner of Patents & Trademarks, Box Assignments  
Washington, D.C. 20231

11046 U.S. PTO  
10/154463  
05/23/02

ASSIGNMENT

WHEREAS, we, TSU SHIH and SUNG-MING JANG, have invented certain improvements in

METHOD OF REPLICATING ALIGNMENT MARKS FOR  
SEMICONDUCTOR WAFER PHOTOLITHOGRAPHY

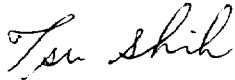
for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

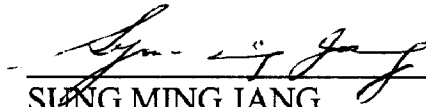
NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, we, TSU SHIH and SUNG-MING JANG, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the 28 day of Feb., 2002, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application

thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.



\_\_\_\_\_  
TSU SHIH



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SUNG MING JANG

**TUNG & ASSOCIATES**  
**838 W. Long Lake Road**  
**Suite 120**  
**Bloomfield Hills, Michigan 48302**